1. Package summary

Terminal position code B (bottom)

Package type descriptive code WLCSP

Package type industry code WLCSP4

Package style descriptive code WLCSP (wafer level chip-size package)

Package body material type X (other)

Mounting method type S (surface mount)

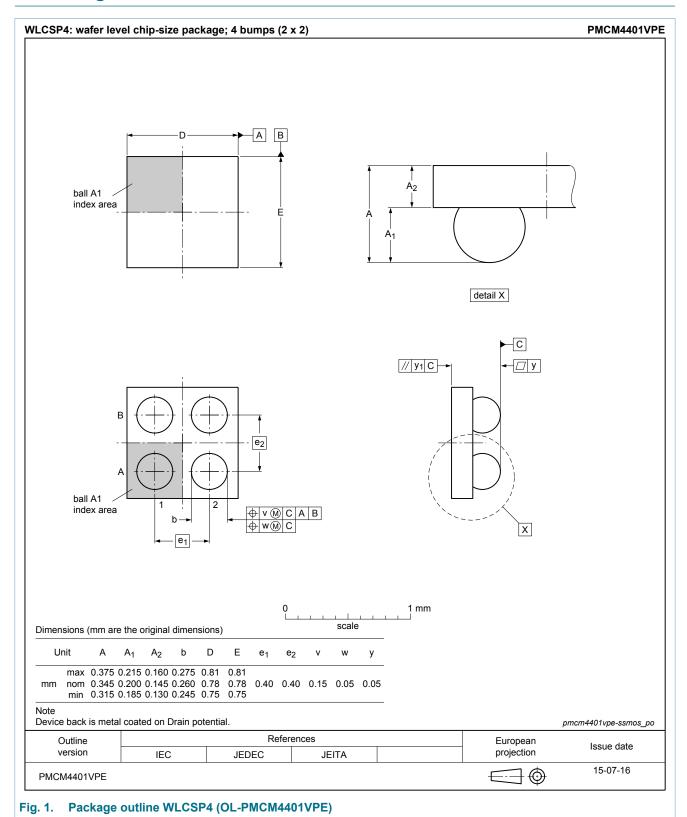
Issue date20-7-2015Manufacturer package codeWLCSP4

Table 1. Package summary

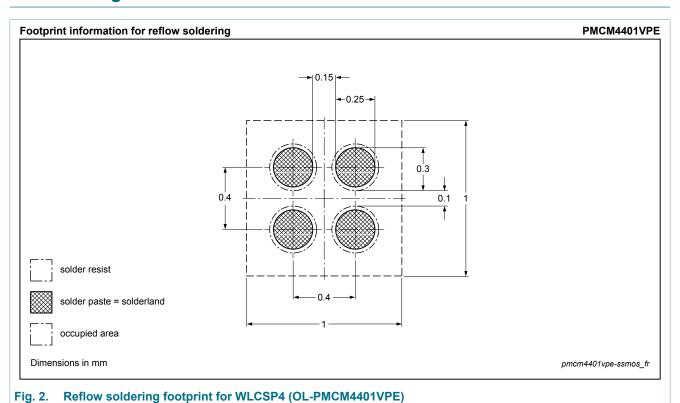
Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	0.75	-	0.78	0.81	mm
E	package width	0.75	-	0.78	0.81	mm
Α	seated height	0.315	-	0.345	0.375	mm
A ₂	package height	0.13	-	0.145	0.16	mm
е	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	4	-	



2. Package outline



3. Soldering



4. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of Nexperia.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

5. Contents

1.	Package summary	1
2.	Package outline	2
3.	Soldering	3
4.	Legal information	4

For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 7 June 2017

[©] Nexperia B.V. 2017. All rights reserved